

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Original) An apparatus, comprising:
an adhesion layer abutting a conductive pad;
a molybdenum-containing barrier layer abutting said adhesion layer;
a wetting layer abutting said molybdenum-containing barrier layer; and
high tin content solder material abutting said wetting layer.
2. (Original) The apparatus of claim 1, wherein said molybdenum-containing barrier layer comprises a material containing at least about 90% (atomic) molybdenum.
3. (Original) The apparatus of claim 1, wherein said high tin content solder material comprises a material containing at least about 90% (by weight) tin.
4. (Original) The apparatus of claim 1, further comprising said conductive pad abutting at least one layer of low k dielectric material.
5. (Original) The apparatus of claim 4, wherein said at least one layer of low-k dielectric material comprises at least one layer of carbon doped oxide.

6. (Original) The apparatus of claim 1, wherein said wetting layer is substantially subsumed in said high tin content solder material forming an intermetallic compound layer.

7.-20. (Canceled)